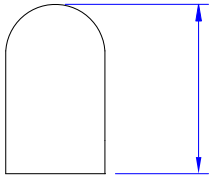
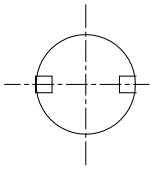
Features

- Pb free product RoHS compliant
- Low power consumption, High efficiency
- General purpose leads
- Reliable and rugged
- Long life solid state reliability
- Radiant angle: 35 °

Package Dimension





Part NO.	Chip Material	Lens Color
LG-03IR4C94C-3034A	AlGaAs/Si	Water Clear

Notes:

1. All dimensions are in millimeters.
2. Tolerance is 0.20mm unless otherwise noted.
3. Protruded resin under flange is 1.0mm max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25

Parameter	MAX.	Unit
Power Dissipation	165	mW
Continuous Forward Current	100	mA
Peak Forward Current[*3]	1.0	A
Reverse Voltage	5	V
Operating Temperature	-40 to + 85	
Storage Temperature	-40 to + 100	
Lead Soldering Temperature [2mm From Body]	260 for 3 Seconds	
Lead Soldering Temperature [5mm From Body]	260 for 5 Seconds	

1. Storage

The storage ambient for the LEDs should not exceed 30℃ temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

2. Precautions in handling:

When soldering, leave 2mm of minimum clearance from the resin to the soldering point.

Dipping the resin to solder must be avoided.

Correcting the soldered position after soldering must be avoided.

In soldering, do not apply any stress to the lead frame particularly when heated.

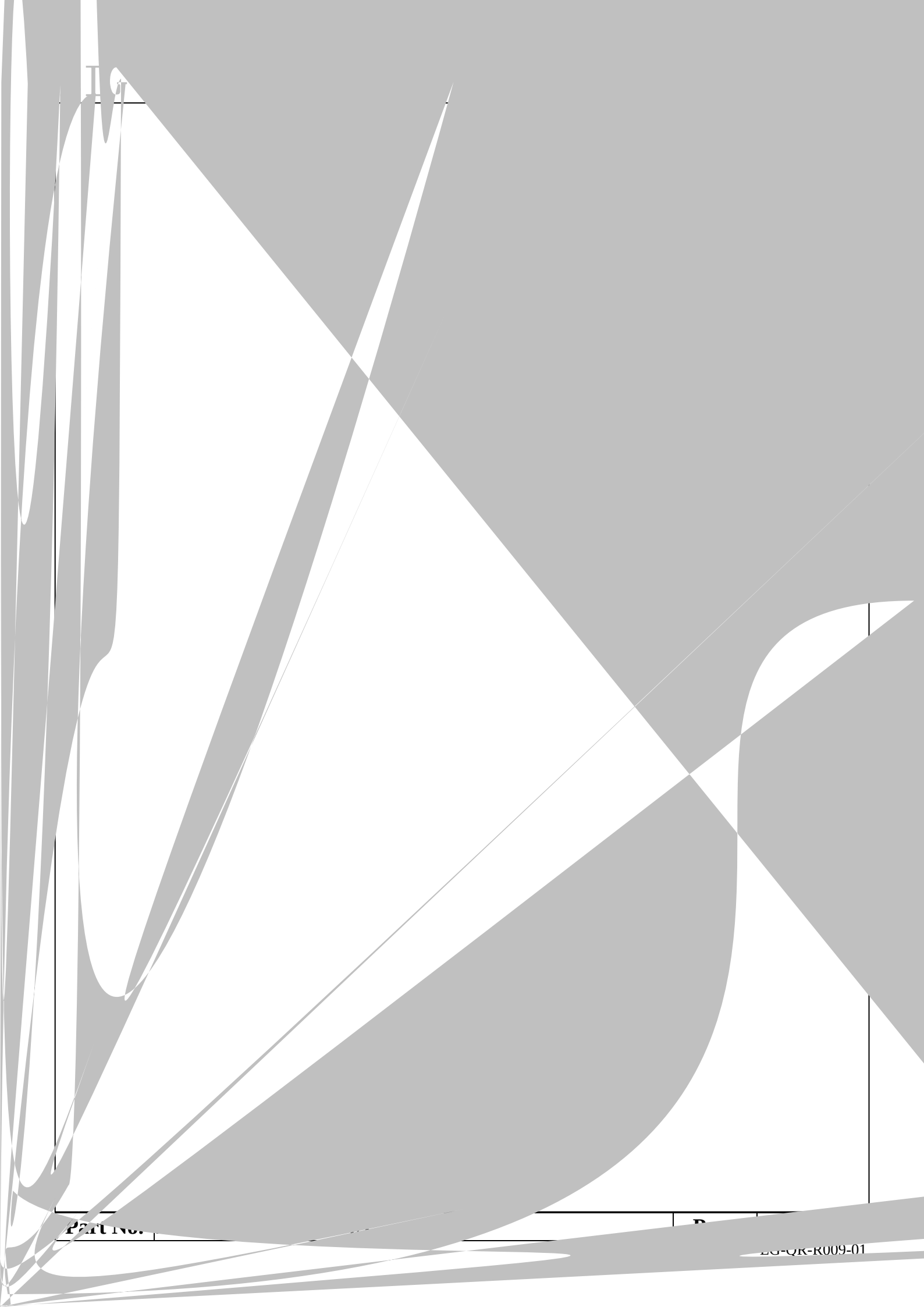
When forming a lead, make sure not to apply any stress inside the resin.

Lead forming must be done before soldering.

It is necessary to cut the lead frame at normal temperature.

3. Peak Forward Current:

Condition for is IFP pulse 0.1ms and duty 1%.



LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

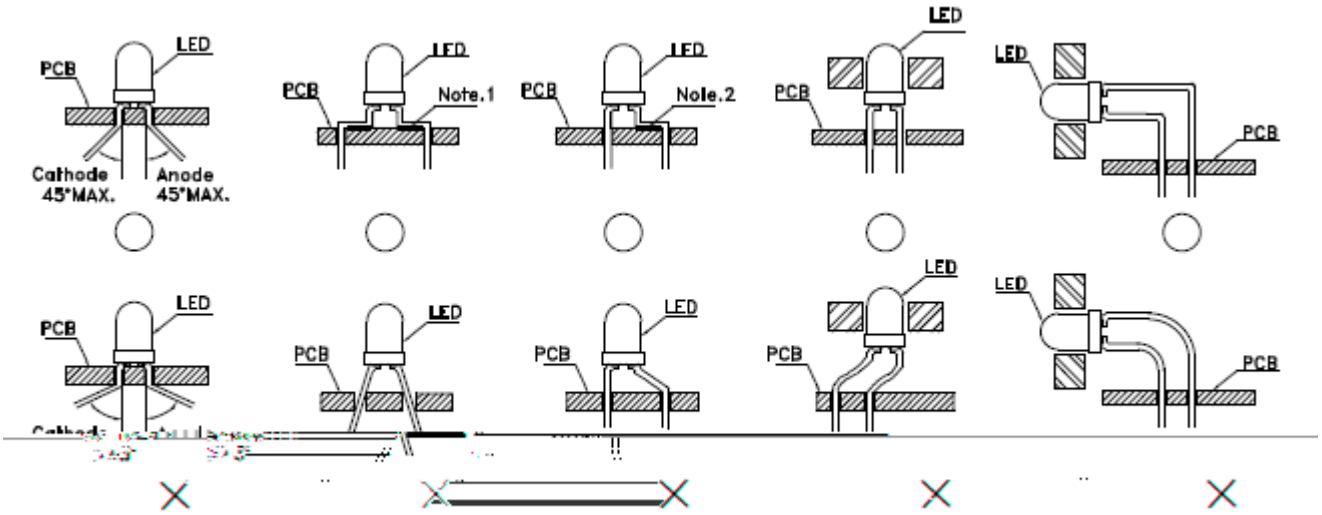


Fig. 1

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

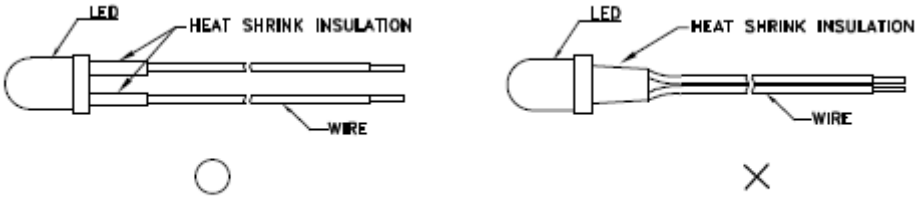


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

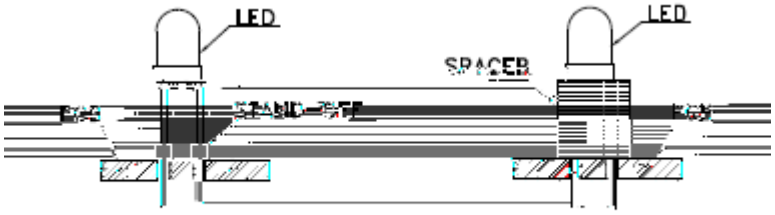
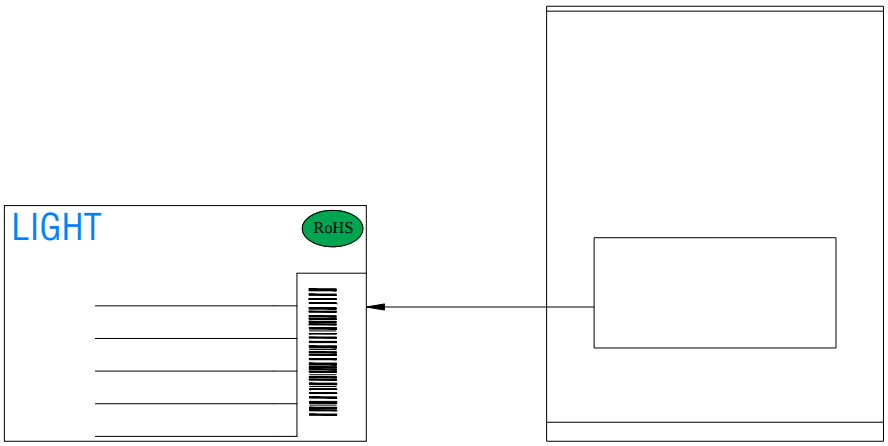
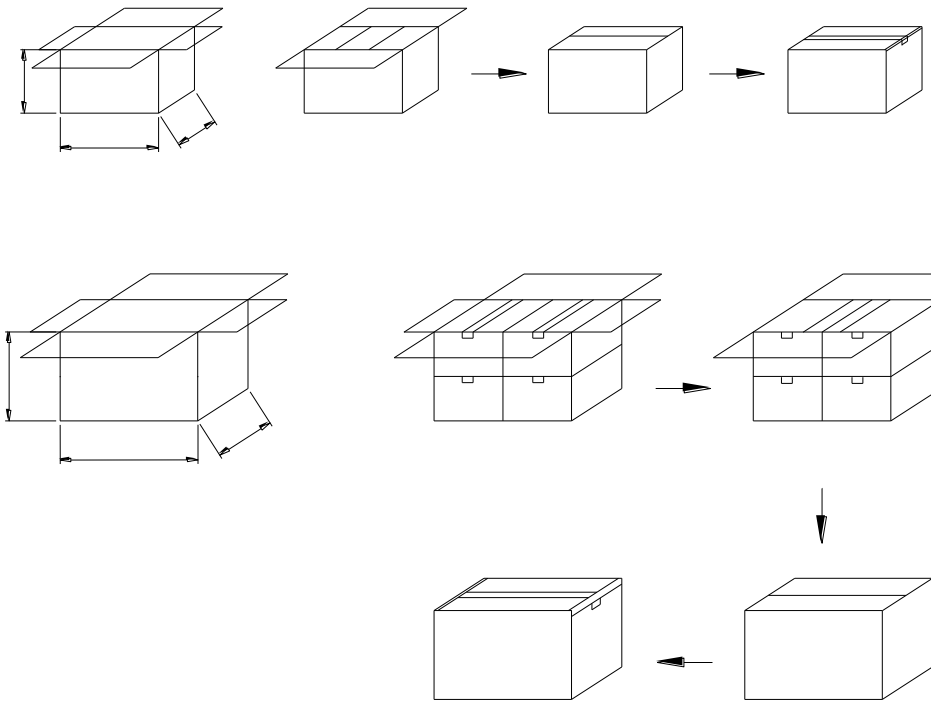


Fig. 3 Fig. 4

PACKAGE



Bag



Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner box volume (Bag / box)	Outer carton volume (Box / Carton)
250	1000	10	4

Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 50mA)

BIN CODE	Min. (mW/sr)	Max. (mW/sr)
15	30	45
16	45	68

NOTE: The Ie guarantee should be added ±15% tolerance.